



## Material Content Data Sheet



<b>Sales Product Name</b>		IPG20N04S4-12A		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000965574						
<b>Package</b>		PG-TDSON-8-10		<b>Weight*</b>		98.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.736	1.76	1.76	17630	17630
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	iron	7439-89-6	0.046	0.05		472	
	non noble metal	copper	7440-50-8	46.380	47.10	47.16	470906	471519
	non noble metal	aluminium	7429-90-5	0.741	0.75	0.75	7527	7527
wire	non noble metal	aluminium	7429-90-5	0.741	0.75	0.75	7527	7527
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		920	
	plastics	epoxy resin	-	6.431	6.53		65298	
	inorganic material	silicondioxide	60676-86-0	38.769	39.36	45.98	393628	459846
leadfinish	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14178	14178
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6123	6138
solder	non noble metal	tin	7440-31-5	0.046	0.05		463	
	noble metal	silver	7440-22-4	0.057	0.06		579	
	non noble metal	lead	7439-92-1	2.179	2.21	2.32	22120	23162
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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